

Compound semiconductors for wireless and optical communications – Europe

Organizers: Gorham Advanced Materials
www.goradv.com

June 17 – 19, 2002
Venue: Radisson SAS Scandinavia Hotel,
Copenhagen, Denmark

The forum will concentrate on the major technology and-business issues related to current and future compound semiconductor use in Europe, and will cover advances in technology for materials and devices, markets, business opportunities, and current and emerging real world applications for the leading compound semiconductor materials.

The Radisson SAS Scandinavia Hotel is a few minutes walk from the centre of old Copenhagen and the Tivoli Gardens, and is 15 minutes from Copenhagen International Airport

The conference fee is \$1,325.00, with the third and subsequent registrants charged at the discounted rate of \$1,125.00 per person. Register online at www.goradv.com/conferences.

Full Technical Programme

Monday - June 17

8:00 am - 12:00 noon - **Optional Workshop: Compounds on Silicon**
(Separate registration fee required, check in from 7:30 am-8:00 am.)
12:00 - 1:00 pm - **Networking Luncheon** for morning and/or afternoon workshop attendees - **Sponsored by Thoughtbeam Inc., A Motorola Company**
1:00 pm - 5:00 pm - **Optional Workshop: Introduction to InP Technology** (Separate registration fee required, check in from 11:30 am-1:00 pm.)
4:00 pm - 6:00 pm - **Conference Registration & Sign-In**
6:00 pm - 7:00 pm - **Welcome Reception**
7:00 pm - 8:30 pm - **Welcome Banquet**
8:30 pm - **Conference Session Commences**

Keynote Session
Communications Will Drive GaAs & High Speed Circuits Market Growth
Stephen Entwistle, Program Director, STRATEGY ANALYTICS LIMITED

Tuesday - June 18

7:00 am - 8:00 am - **Conference Registration & Sign-In.** Join fellow participants for continental breakfast & informal discussion. Continental Breakfast Sponsored by Velocium

8:00 am - **Conference Sessions Commence**
Welcome
Andrew P. Molloy, Sr. Vice President, GORHAM CONFERENCES

Opening Remarks by Co-Chairs
Virginia Houlding, Chief Technologist, MATHESON TRI-GAS
John Hennessy, Marketing Manager, PHILIPS ANALYTICAL

Keynote Session Continues
RF Technologies for Handset Products
James DiLorenzo, President, SIGNAL TECHNOLOGY CORPORATION

Title To Be Announced
Drew Nelson, President & CEO, IQE PLC

Session 1: Trends in Markets and Applications for Compound Semiconductors for Wireless and Optical Communications
Future Trends in Compound Semiconductors in RF, Microwave and mm-Wave Applications
David Smith, Director of Business, FILTRONIC COMPOUND SEMICONDUCTORS LTD.

10:30 am - 11:00 am - **Networking Break** - Sponsored by Compound Semiconductors Online - Matheson Tri-Gas - Philips Analytical

Compound Semiconductor IC Business in Europe for Fiber Optics
Kazuyoshi Asai, Deputy Exec. Director, Electronics Business Group, NTT ELECTRONICS CORPORATION

SiGe and SiGeC: How Might They Impact the III-V Market?
Doug Meyer, Director of Product Marketing, ATMI EPITAXIAL SERVICES

12:00 - 1:30 pm - Networking Luncheon - Sponsored by IQE plc - Signal Technology Corporation - Strategy Analytics Limited

SiGe/CMOS Circuits for Microwave Communications
Bertil Hansson, Senior Research Engineer, ERICSSON AB

Session 2: Status and Prospects--Compound Semiconductor Materials, Devices, and Systems for Wireless, Broadband, and Optical Communications

High-Volume InP Production for Wireless and Optoelectronic Applications
Dwight C. Streit, President, VELOCIMUM, A TRW COMPANY

III-V MMICs Will Continue to Complement Si for Advanced Telecommunication Applications
Marc Rocchi, Chief Technology Officer, OMMIC

3:30 pm - 4:00 pm - Networking Break

Commercialization of Strained Silicon Technology
Mayank T. Bulsara, CTO, AMBERWAVE SYSTEMS CORP.

Volume Production of GaAs Substrates Optimized with Respect to Characteristics and Costs for Device Type and Process Technology

Roland Bindemann, Application Manager, FREIBERGER COMPOUND MATERIALS GMBH

6:00 pm - 8:00 pm - Join colleagues for a complimentary networking cocktail reception.

Wednesday - June 19

7:00 am - 8:00 am - Join colleagues for continental breakfast.

8:00 am - Conference Commences

Opening Remarks by Co-Chair
Gareth Llewellyn,, COMPOUND SEMICONDUCTORS ONLINE

Session 2: Status and Prospects-Compound Semiconductor Materials, Devices, and Systems for Wireless, Broadband, and Optical Communications (continued)

Component Challenges in Optical Communication
Kristian Stubkjaer, Professor, Director, TECHNICAL UNIVERSITY OF DENMARK

Advanced GaAs MMIC Technologies and Designs for Low Cost Millimetre-Wave Telecommunications and Automotive Applications

Dominique Pons, Director, R & D and Strategic Marketing, UNITED MONOLITHIC SEMICONDUCTORS SAS

Session 3: Developments in Manufacturing of Compound Semiconductors: Equipment, Materials and Metrology
Wireless and Optical Communications: High Productivity Manufacturing

Bernd Schulte, Director, Compound Semiconductor Equipment, AIXTRON AG

10:15 am - 10:45 am - Networking Break

Equipment Strategies in Emerging Markets
Bernard Culverhouse, V.P. Marketing, TRIKON TECHNOLOGIES LTD.

Innovative Solutions for Bulk Hydride Gas Delivery: Improving Process Performance, Safety and Cost of Ownership
Virginia Houlding, Director of R&D, MATHESON TRI-GAS

Made to Measure? Standard Products and Standard Tools
John Hennessy, Marketing Manager, PHILIPS ANALYTICAL

12:15 pm - 1:45 pm - Networking Luncheon

Session 4: New and Emerging Materials and Devices: R&D in Compound Semiconductors
New Compound Semiconductor Structures Obtained by Layer Transfer

Bernard Aspar, Leader, Transfer of Films and Circuits Laboratory, CEA / LETI

The Potential of Ge Substrates for Optoelectronic and Electronic Applications
Carl Quaeyhaegens, Business Development, UMICORE USA, INC.

Gallium Nitride Power Transistors: Revolutionizing the Wireless Infrastructure Market
Bob Lynch, President/CEO, NITRONEX CORPORATION

Blue Lasers on Bulk GaN Crystals
Mike Leszczynski, Head, Nitride Epitaxy Lab, UNIPRESS-TOPGAN

InSb - The Next Big Thing?
Tim Phillips, Business Development Manager, QINETIQ LTD.

Closing Remarks by Co-Chairs

3:45 pm - 4:15 pm - Conference Concludes
Post-Conference Refreshments